

FIG. 2

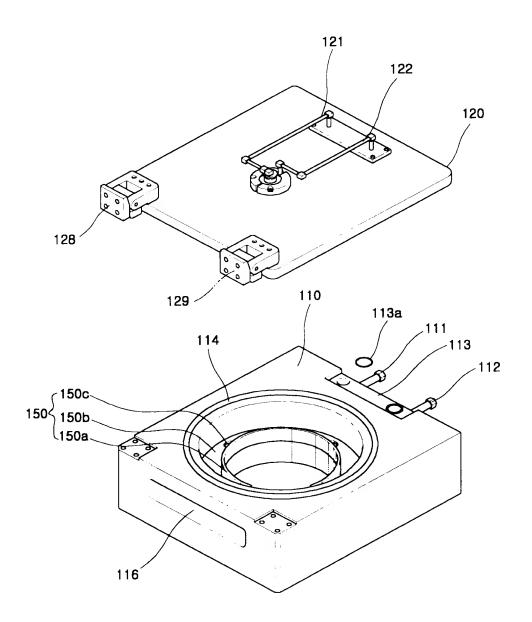


FIG. 3

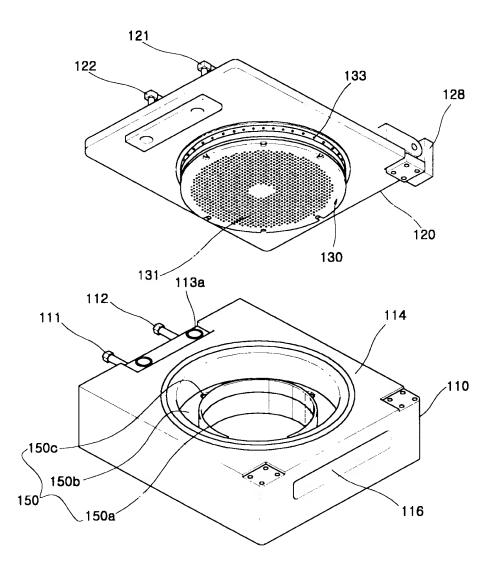


FIG. 4

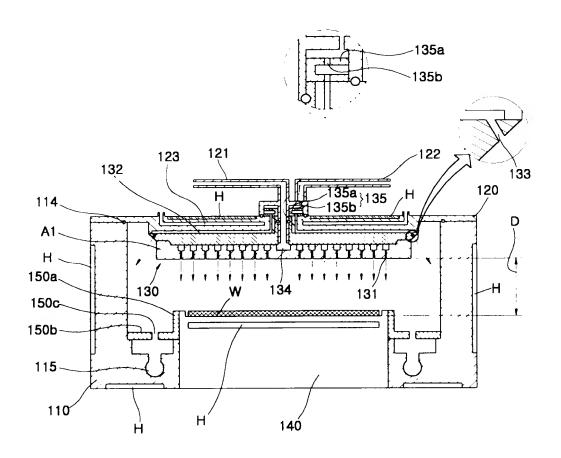


FIG. 5

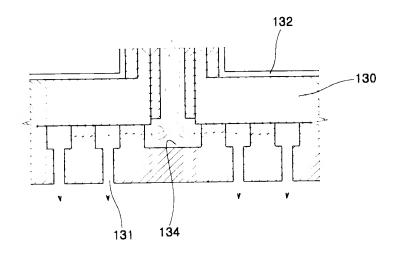
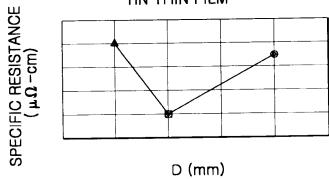


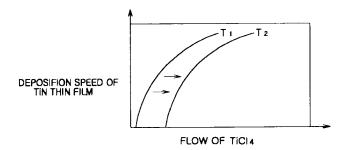
FIG. 6

RELATIONSHIP BETWEEN DISTANCE (D) AND SPECIFIC RESISTANCE UPON DEPOSITION TIN THIN FILM



- SPECIFIC RESISTANCE (A:27¢, B:5¢)
- SPECIFIC RESISTANCE (NO BAFFLE)
 - SPECIFIC RESISTANCE (27\(\phi \times \text{6hole} \))

FIG. 7



CONDITIONS: FIXING OF OTHER PROCESS FACTORS SUCH AS FLOW OF NH3

T 1 : TEMPERATURE OF BOTTOM OF DIFFUSION PLATE

T 2: TEMPERATURE OF BOTTOM OF DIFFUSION PLATE

HERE, T1 < T2

FIG. 8

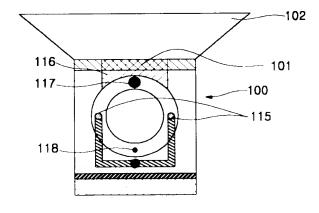
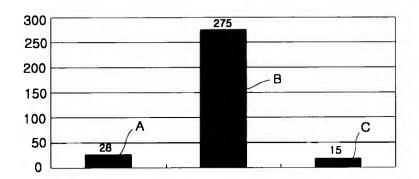


FIG. 9



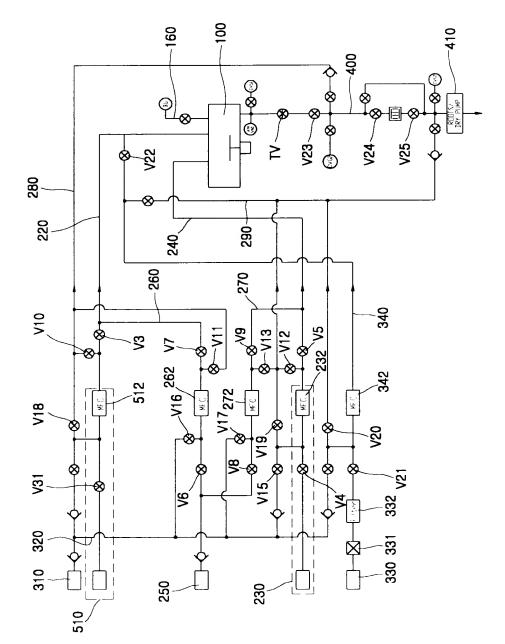


FIG. 11

